



## Material Content Data Sheet



<b>Sales Product Name</b>		TLE4966-3K		<b>Issued</b>		28. August 2013		
<b>MA#</b>		MA000866708						
<b>Package</b>		PG-TSOP6-6-5		<b>Weight*</b>		13.46 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.856	6.36	6.36	63596	63596
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		81	
	non noble metal	titanium	7440-32-6	0.005	0.04		404	
	non noble metal	chromium	7440-47-3	0.016	0.12		1211	
	non noble metal	copper	7440-50-8	5.414	40.21	40.38	402079	403775
wire	noble metal	gold	7440-57-5	0.021	0.15	0.15	1543	1543
encapsulation	organic material	carbon black	1333-86-4	0.050	0.37		3734	
	plastics	brominated resin	-	0.063	0.47		4667	
	inorganic material	antimonytrioxide	1309-64-4	0.126	0.93		9335	
	plastics	epoxy resin	-	1.144	8.49		84946	
	inorganic material	silicondioxide	60676-86-0	4.902	36.41	46.67	364056	466738
leadfinish	non noble metal	tin	7440-31-5	0.299	2.22	2.22	22200	22200
plating	noble metal	silver	7440-22-4	0.155	1.15	1.15	11479	11479
glue	plastics	epoxy resin	-	0.072	0.54		5367	
	noble metal	silver	7440-22-4	0.341	2.53	3.07	25302	30669
*deviation	< 10%				Sum in total:		100,00	1000000

### Important Remarks:

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